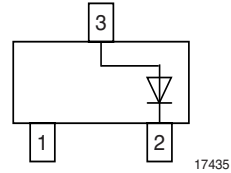
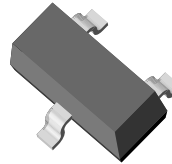


Small Signal Fast Switching Diode

Features

- Fast switching speed
- Surface mount package
- Well suited for automated assembly process
- Lead (Pb)-free component
- Component in accordance to RoHS 2002/95/EC and WEEE 2002/96/EC



17435

Mechanical Data

Case: SOT23 Plastic case

Weight: approx. 8.0 mg

GS18/10 k per 13" reel (8 mm tape), 10 k/box

Packaging Codes/Options:

GS08/3 k per 7" reel (8 mm tape), 15 k/box

Parts Table

Part	Ordering code	Type Marking	Remarks
BAL99-V	BAL99-V-GS18 or BAL99-V-GS08	JF	Tape and Reel

Absolute Maximum Ratings

 $T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

Parameter	Test condition	Symbol	Value	Unit
Repetitive peak reverse voltage = Working peak reverse voltage = DC Blocking voltage		$V_{RRM} = V_{RWM} = V_R$	70	V
Peak forward surge current	$t = 1\text{ }\mu\text{s}$	I_{FSM}	2	A
	$t = 1\text{ ms}$	I_{FSM}	1	A
	$t = 1\text{ s}$	I_{FSM}	0.5	A
Average forward current		I_{FAV}	250	mA
Power dissipation	on fiberglass substrate 30 mm x 10 mm x 1.6 mm	P_{tot}	350	mW

Thermal Characteristics

 $T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified

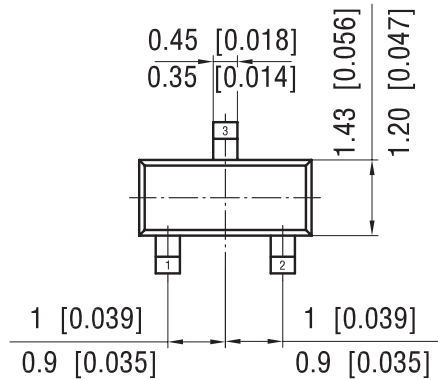
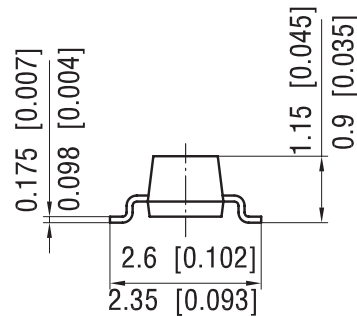
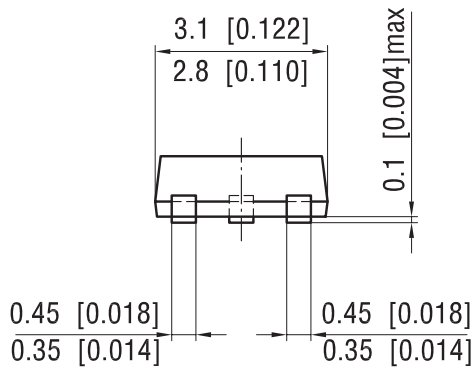
Parameter	Test condition	Symbol	Value	Unit
Thermal resistance junction to ambient air	on fiberglass substrate 30 mm x 10 mm x 1.6 mm	R_{thJA}	357	K/W
Junction temperature		T_j	150	$^{\circ}\text{C}$
Storage temperature range		T_{stg}	- 55 to + 150	$^{\circ}\text{C}$

Electrical Characteristics

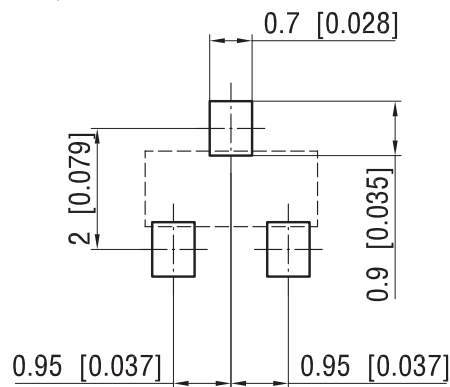
T_{amb} = 25 °C, unless otherwise specified

Parameter	Test condition	Symbol	Min	Typ.	Max	Unit
Forward voltage	I _F = 1 mA	V _F			715	mV
	I _F = 10 mA	V _F			855	mV
	I _F = 50 mA	V _F			1000	mV
	I _F = 150 mA	V _F			1250	mV
Reverse current	V _R = 70 V	I _R			2.5	μA
	V _R = 70 V, T _j = 150 °C	I _R			100	μA
	V _R = 25 V, T _j = 150 °C	I _R			30	μA
Diode capacitance	V _F = V _R = 0, f = 1 MHz	C _D			1.5	pF
Reverse recovery time	I _F = I _R = 10 mA to I _R = 1 mA, R _L = 100 Ω, V _R = 6 V	t _{rr}			6	ns

Package Dimensions in mm (Inches): SOT23



foot print recommendation:



Document no.: 6.541-5014.01-4
Rev. 6 - Date: 08.July.2004
17418



Ozone Depleting Substances Policy Statement

It is the policy of Vishay Semiconductor GmbH to

1. Meet all present and future national and international statutory requirements.
2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

It is particular concern to control or eliminate releases of those substances into the atmosphere which are known as ozone depleting substances (ODSs).

The Montreal Protocol (1987) and its London Amendments (1990) intend to severely restrict the use of ODSs and forbid their use within the next ten years. Various national and international initiatives are pressing for an earlier ban on these substances.

Vishay Semiconductor GmbH has been able to use its policy of continuous improvements to eliminate the use of ODSs listed in the following documents.

1. Annex A, B and list of transitional substances of the Montreal Protocol and the London Amendments respectively
2. Class I and II ozone depleting substances in the Clean Air Act Amendments of 1990 by the Environmental Protection Agency (EPA) in the USA
3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

Vishay Semiconductor GmbH can certify that our semiconductors are not manufactured with ozone depleting substances and do not contain such substances.

We reserve the right to make changes to improve technical design and may do so without further notice.

Parameters can vary in different applications. All operating parameters must be validated for each customer application by the customer. Should the buyer use Vishay Semiconductors products for any unintended or unauthorized application, the buyer shall indemnify Vishay Semiconductors against all claims, costs, damages, and expenses, arising out of, directly or indirectly, any claim of personal damage, injury or death associated with such unintended or unauthorized use.

Vishay Semiconductor GmbH, P.O.B. 3535, D-74025 Heilbronn, Germany



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